U.S. Department of Commerce, Patent and Trademark Office	Atty. Docket No.	Serial No.
	M-15302-1P US	10/798,540
INFORMATION DISCLOSURE STATEMENT BY APPLICANT	Applicant(s)	
(Use several sheets if necessary)	Savastiouk et al.	
	Filing Date	Group
	March 10, 2004	Unassigned

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*Examiner Initial		Document Number	Date	Name	Class	Subclass	Filing Date If Appropriate
KL	AA	6,175,158	16 Jan. 2001	Degani et al.			
KL	AB	6,661,088	9 Dec. 2003	Yoda et al.			
KL	AC	2002/0036340	28 Mar. 2002	Matsuo et al.			
KL	AD	2003/0047798	13 Mar. 2003	Halahan			
KL	AE	2002/0074637	20 Jun. 2002	McFarland			
KL	AF	2002/0175421	28 Nov. 2002	Kimura			
KL	AG	2003/0080437	1 May 2003	Gonzalez et al.			
KL	AH	2002/0048916	25 Apr. 2002	Yanagida			
[illegible]	AI						

Foreign Patent Documents

		Document	Date	Country	Class	Subclass	Translation Yes	Translation No

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